ElectronicsForU Network : July Ed. of India Technology Week @Home 2020

# Chips for GreenTech: What will Change?

Gaurav Gupta, Ph.D. 15-July-2020

https://www.linkedin.com/in/gaurav-gupta-1205399/ https://www.quora.com/profile/Gaurav-Gupta-1977

### Outline

- Why and Why Now: Energy Crisis
- Traditional Approach: Scaling Nodes
  - New Approach:

#### Novel

- **Materials Transistors Circuits Architectures**
- Enabling New Applications
- Scope for India (Discussion)
- Testing (Discussion)
- Fab/Factory vs Outsource (Discussion)
- Volume (Local Market vs Global Market) (Discussion)

Why?

# **Energy Crisis**

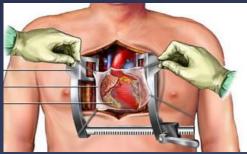


200 Trillion-Watt-hr. consumed in 2015 by Data Servers [1] !

Save Energy. Save Earth

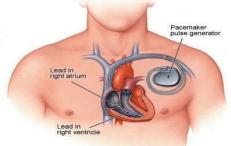


#### No need to repeatedly operate to Replace Implants



Save Lives & Money (Bioelectronics)

Battery Drainage requires operation to replace implant





Explosion of devices & energy demand

Clean & Smart Environment



# **Objective**

#### Traditional Computing Chips



Large Static + Dynamic Power Dissipation

But, this is going to be "Very Very" Application Specific

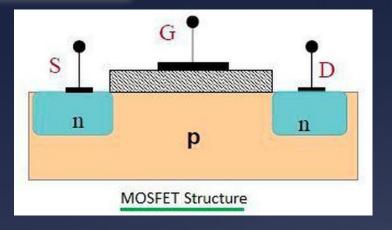
#### Future Computing Chips

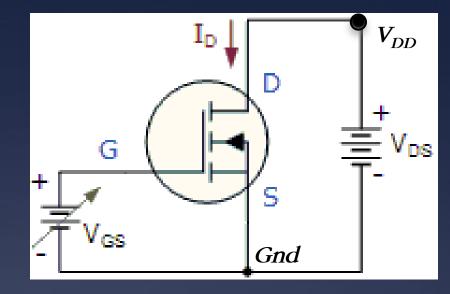


- Robust Transport
- Minimum leakage of current & energy (as heat)
- Task accomplished by consuming smaller amount of energy
- Zero Standby Power with much smaller break-even time and power

#### Traditional Approach

# **Node Scaling**



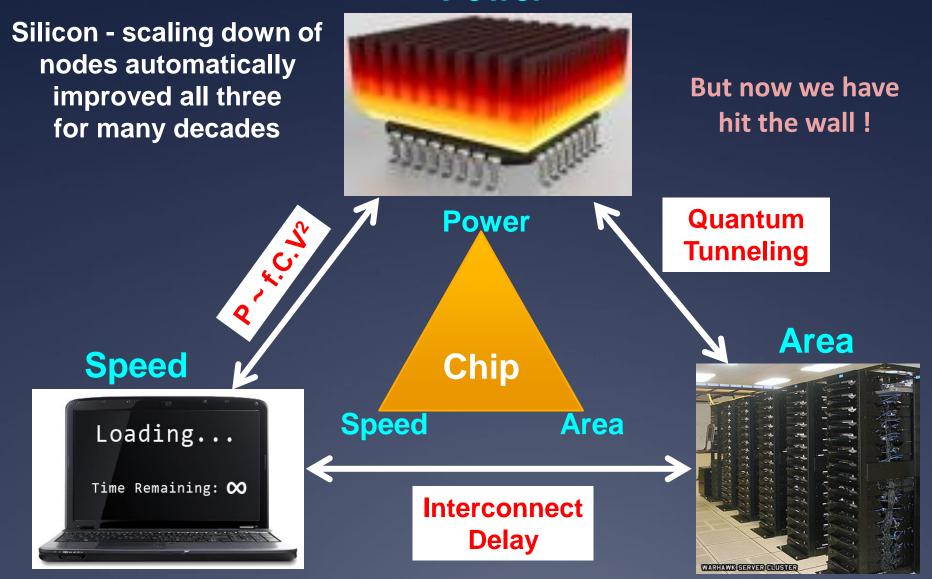


#### Scale:

- ➢ Bias Voltage V<sub>DD</sub>
- Dimensions Channel Length, Fins
- > High-K Gate Materials (HfO<sub>2</sub>)
- Strained Transistors
- > Clock Frequency
- > Parallelism

Accomplish same task with lower energy/power consumption. i.e. femto-Joules consumed for toggling 1-bit

#### Standard Trilemma Power

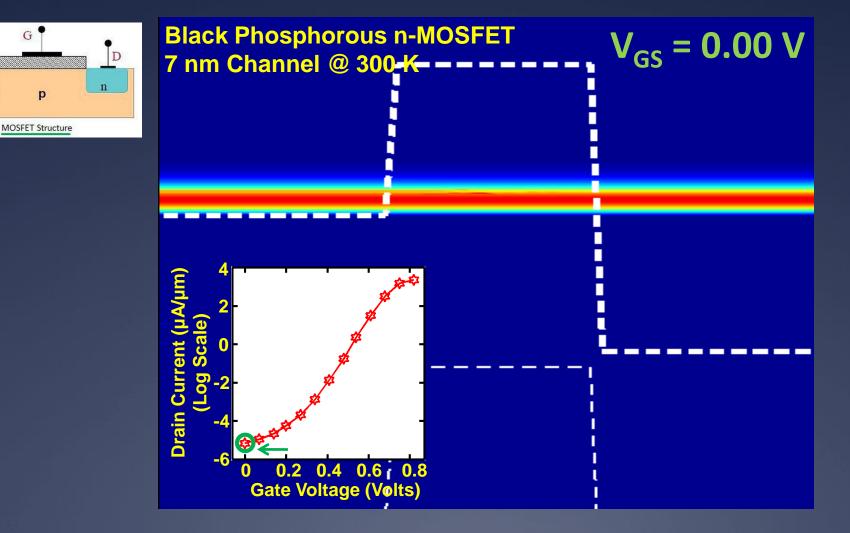


# **Quantum Transport Simulation of 7 nm Black Phosphorus Transistor**

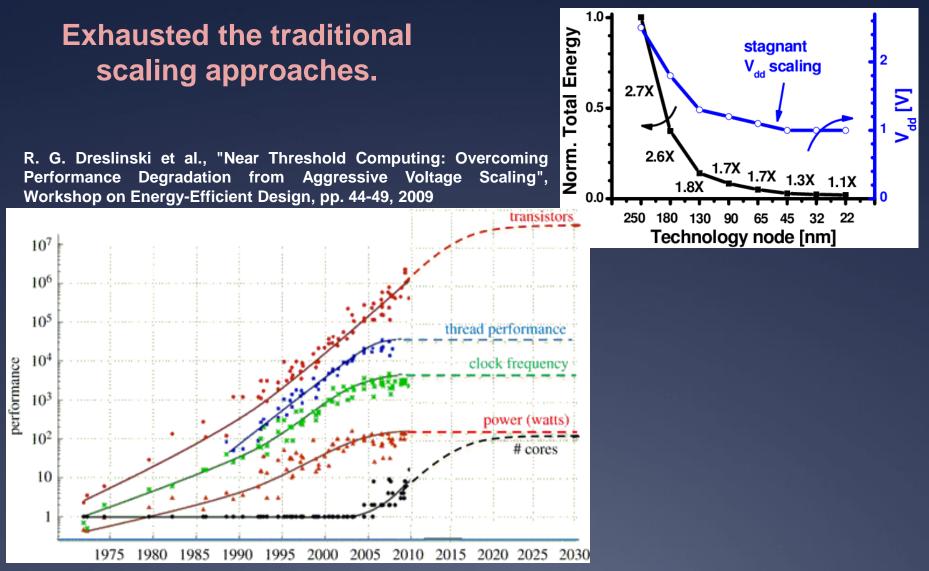
**Observe the leakage through the bandgap** 

S

n



## End of evolution of GreenTech Chips?



John Shalf, "The future of computing beyond Moore's Law", Philosophical Transactions of the Royal Society A: Mathematical, Physical and Engineering Sciences, vol. 378, issue 2166, 2020

Can we continue improving the energy and power efficiency of Chips ?

Of course **Yes** 

Otherwise we won't be having this webinar

So let's see:

- > How
- > Where does it lead us (if time permits)
- What sort of future they can unfold (if time permits)

#### New Approach

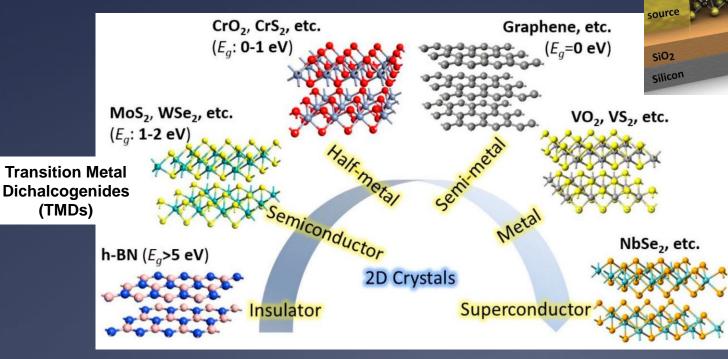
# **Broad Classification**

<ul> <li>Materials &amp; their combinations</li> <li>Low Power Segment</li> <li>2D Materials, Topological Insulators (TIs)</li> <li>High-Power Segment</li> <li>Wide-Bandgap Semiconductors</li> </ul>		<ul> <li>ctronics Transistors</li> <li>Tunneling Field Effect Transistors (TFETs)</li> <li>Van der Waals heterostructures based FETs</li> <li>Negative-Capacitance Field Effect Transistors (NC-FETs)</li> <li>Selectors</li> </ul>						
					Circuits			
						IC De	esign	Architectures

#### **Materials**

# **2D Materials**

- Atoms in single layer
- Typically lesser scattering (absence of bonds in perpendicular direction):
  - Longer mean-free path
  - Higher mobility
- Robust electron transport



M. R. E. Tanjil et al., "Ångström-Scale, Atomically Thin 2D Materials for Corrosion Mitigation and Passivation", Coatings, 9(2), pp. 133, 2019 top gate

MoS<sub>2</sub>

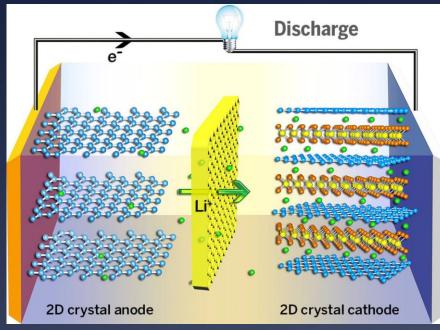
https://physicsworld

.com/a/molybdenite-

transistor-is-a-first/

# 2D Material Applications Computing

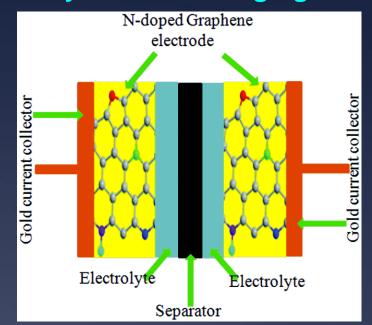
Future batteries with high energy density and fast charging

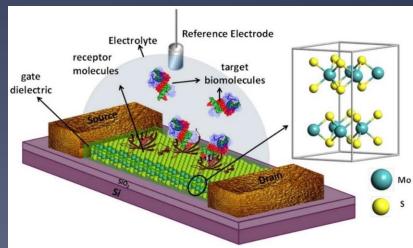


Top Left: F. Bonaccorso et al., "Graphene, related two-dimensional crystals, and hybrid systems for energy conversion and storage", Science, Vol. 347, Issue 6217, pp. 1246501, 2015 ; Top Right: E. Haque et al., "Nitrogen doped graphene via thermal treatment of composite solid precursors as a high performance supercapacitor", RSC Adv., vol. 5, pp. 30679-30686, 2015

#### Bio-Sensors better SNR → lower resolution ADC → less energy consumption

K. Shavanova et al., "Application of 2D Non-Graphene Materials and 2D Oxide Nanostructures for Biosensing Technology", Sensors 16(2), 223, 2016

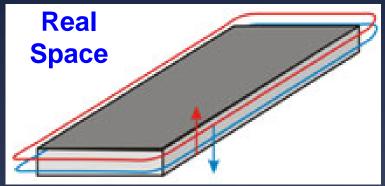




# **Topological Insulator (TI)**

#### **Nobel Prize 2016 Physics:** topological phase transitions and topological phases of matter

https://www-ssrl.slac.stanford.edu/ research/highlights\_archive/topological\_insulator.html



#### 2D-TI (QSH Phase) Spins flow on edges

Momentum Axis of electron spin Space Insulator LUSTRATION: EMILY COOPE

#### **3D-TI – Spins flow on Surface**

http://spectrum.ieee.org/image/1876231



# **Electron Transport in Topological Insulators**

#### **Back-scattering Prohibited**

unless:

> Spin-Flip Mechanisms (Magnetic Impurities)

> Break Time-Reversal Symmetry (Magnetic-Field)

#### **Excellent Material for Transport and Electronic Devices**

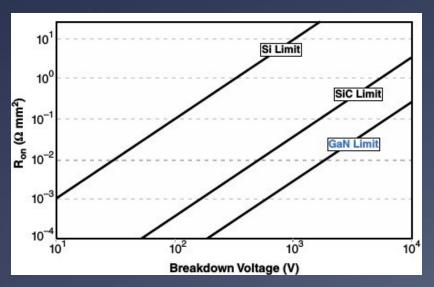
#### Hypothesis :

- Perfect Transport
- No Heat Dissipation in the Channel (proven for HgTe 2D-TI edge transport)

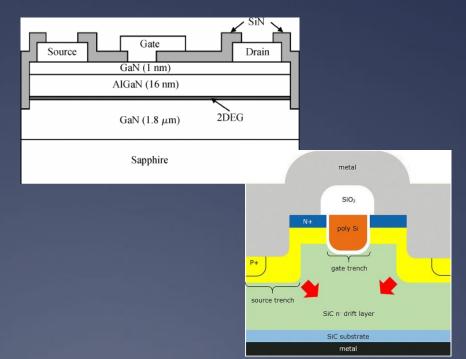
# Wide-bandgap (WBG) Semiconductors

#### Gallium Nitride (GaN) and Silicon Carbide (SiC): Power Applications

Table 1.1 Material properties of Silicon, GaN, and SiC						
Parameter		Silicon	GaN	SiC		
Band Gap E <sub>g</sub>	eV	1.12	3.39	3.26		
Critical Field E <sub>Crit</sub>	MV/cm	0.23	3.3	2.2		
Electron Mobility µn	cm <sup>2</sup> /V·s	1400	1500	950		
Permittivity ε <sub>r</sub>		11.8	9	9.7		
Thermal Conductivity $\lambda$	W/cm·K	1.5	1.3	3.8		



Both Table and R<sub>on</sub> plot: Chap 1. GaN Transistors for Efficient Power Conversion by Alex Lidow

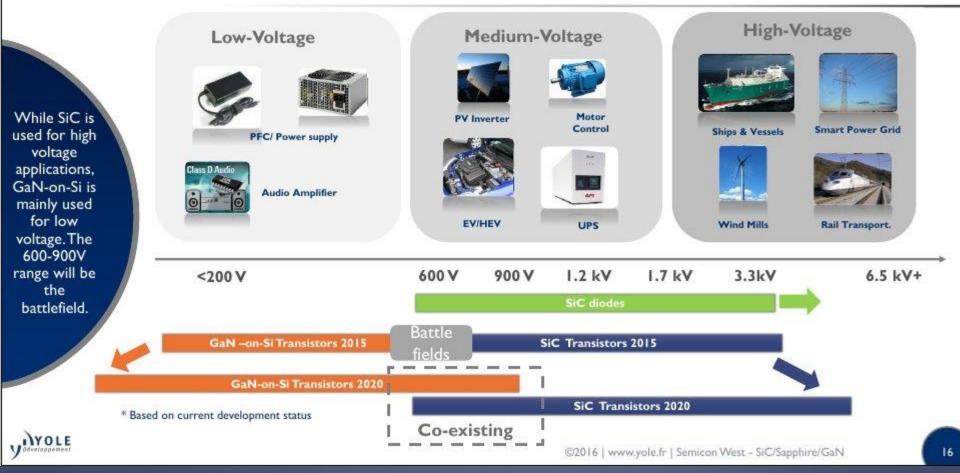


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# **WBG** Applications

#### WBG MARKET SEGMENTATION AS A FUNCTION OF VOLTAGE RANGE

#### Current status and Yole's vision for 2020\*



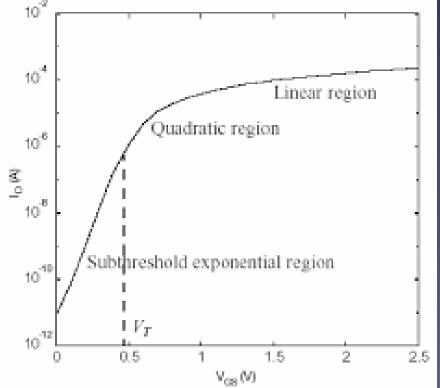
SiC, Sapphire, GaN... : what is the business evolution of the non-Silicon based semiconductor industry?, Yole Report, 2016

#### Transistors

# Sub-Threshold Slope (SS)

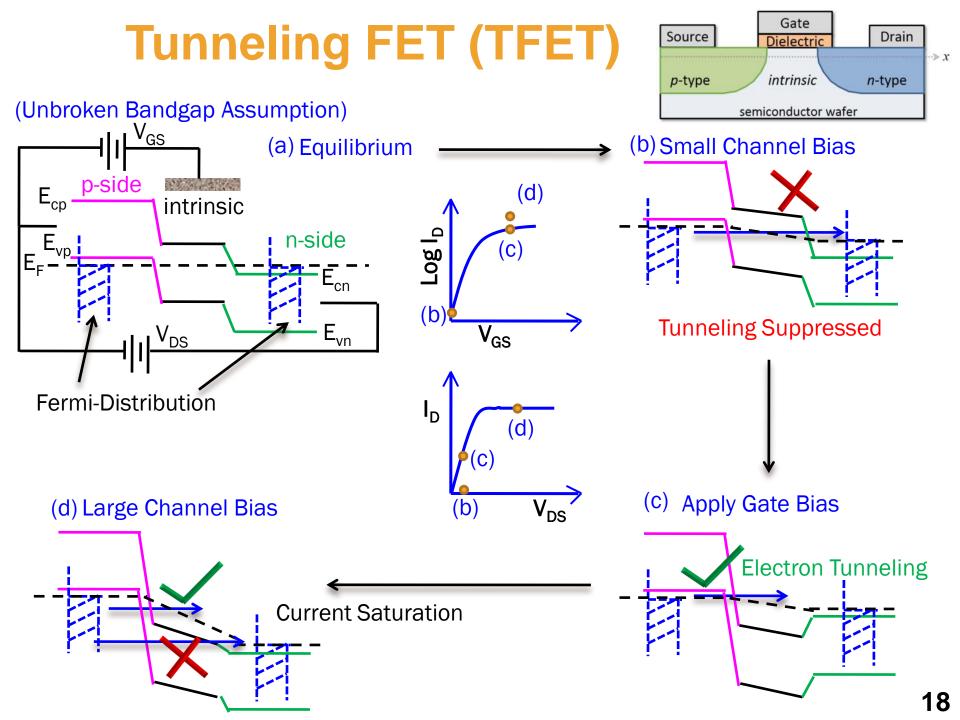
Within the available gate voltage swing, , low SS is required for:

- high "switch-on current" (I<sub>ON</sub>) for faster charging of load capacitors
- low switch-off current (I<sub>OFF</sub>) for lower static dissipation
- MOSFETs ideal case 60 mV/decade @ 300 K (limited by thermionic emission over the barrier)

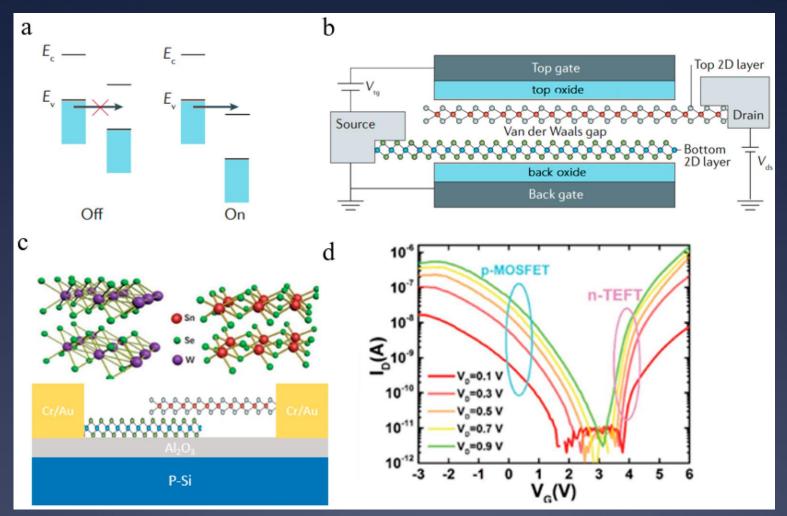


$$SS = \ln(10)\frac{k_{\rm B}T}{q} \left(1 + \frac{C_{\rm d}}{C_{\rm ox}}\right)$$

 $k_B$  is Boltzmann's constant T is the temperature q the elementary charge  $C_d$  the depletion layer capacitance  $C_{ox}$  the gate-oxide capacitance.



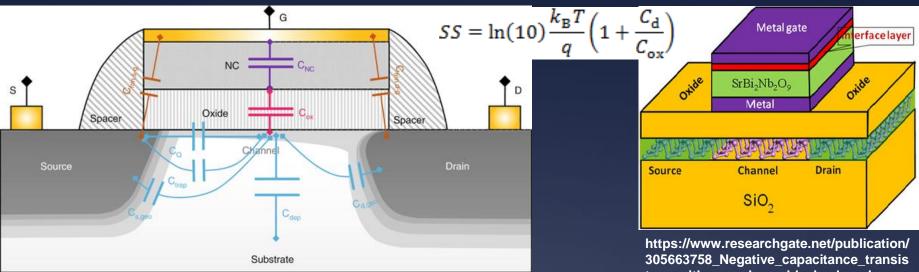
### Van der Waals Heterostructure FETs



J. Li et al., "Van der Waals Heterostructure Based Field Effect Transistor Application", Crystals , 8(1), pp. 8, 2018

- Larger cross-section enables more current
- Robust transport in both atomic layers  $\rightarrow$  lower heat dissipation

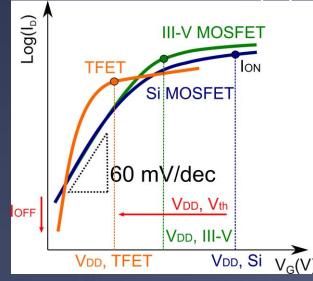
### **Negative Capacitance FET**



https://www.nature.com/articles/s41928-020-0377-0

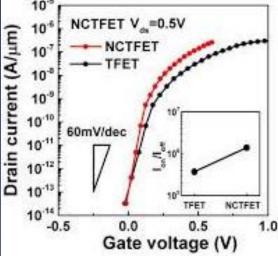
tors with monolayer black phosphorus

Negative Capacitance Gates: Ferroelectric Materials like  $Pb[Zr_{x}Ti_{(1-x)}]O_{3}$  (PZT),  $Hf_{0.5}Zr_{0.5}O_{2}$  (HfZrO),  $SrTiO_{3}$  (STO)



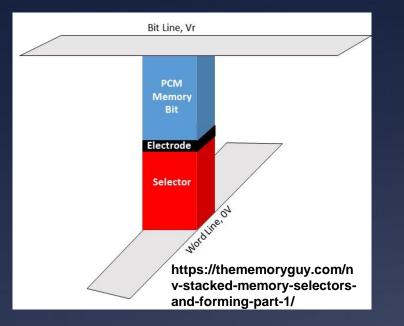
https://www.zurich.ibm.com/st/ nanophotonics/tunneling.html

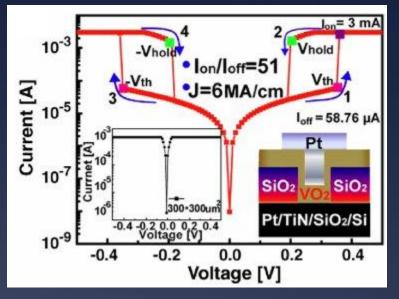
> https://e3s-center.berkeley.edu/wpcontent/uploads/2017/09/2-1-1 Kobayashi.pdf



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#### **Selectors**





G. W. Burr et al., "Access devices for 3D crosspoint memory", Journal of Vacuum Science & Technology B 32, 040802 (2014)

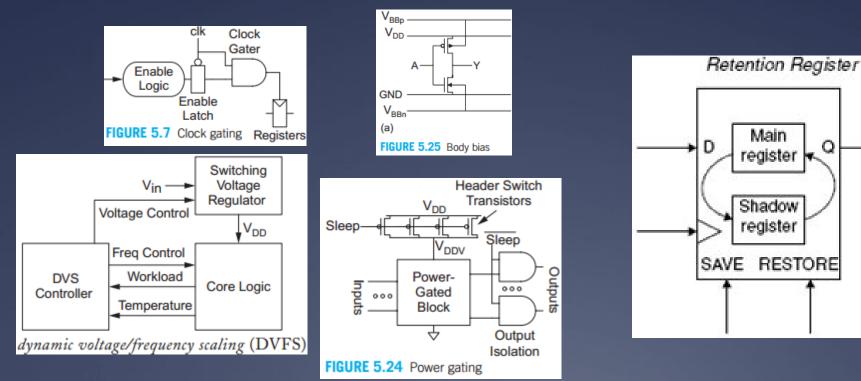
- Two-Terminal Device (multi-layer stack of materials) to replace MOSFET especially for 3D-Memories
- > On-Off like MOSFET
- On vs Off depends on direction of current flow through them
- MOSFET can only be grown as part of FEOL, but these can be part of BEOL

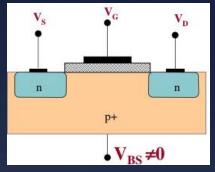
#### Circuits

#### Chapter 5, CMOS VLSI Design – Weste, 4th edition

# **Low Power Schemes**

- **Body Voltage & Multi-Threshold** 1.
- Reduce/Multi V<sub>DD</sub> 2.
- 3. **Reduce/Multi Freq.**
- **Clock Gating** 4.
- 5. Store-in on-chip memory:- a. Volatile **b.** Non-Volatile
- **Retention Registers:-**6.
- **Complete Power-Off (Power-Gating)** 7.



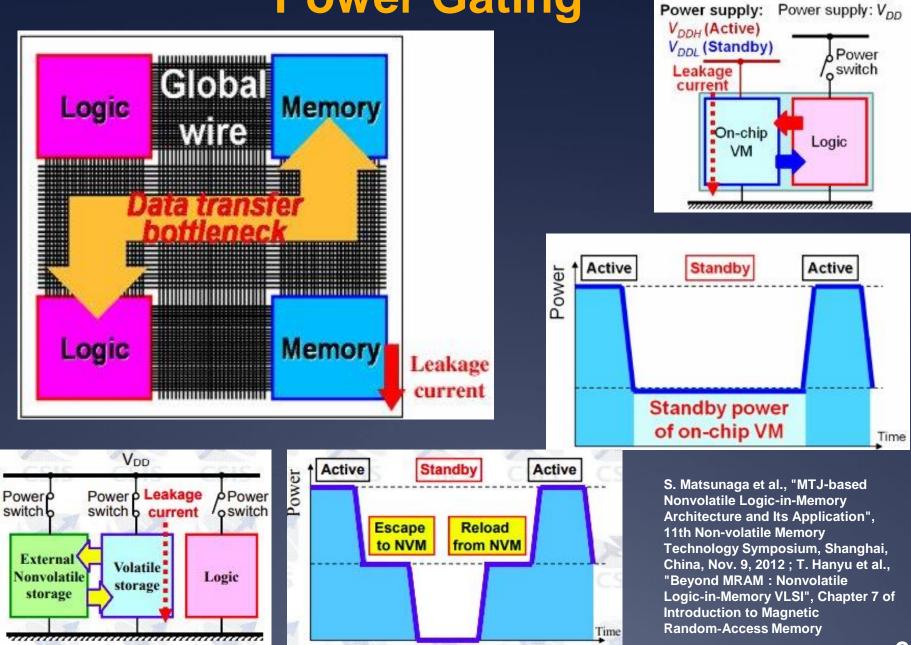


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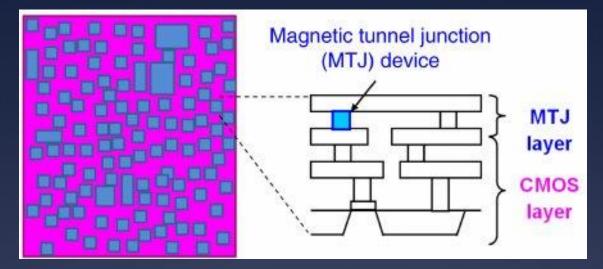
<u>a.</u> Volatile **b.** Non-Volatile

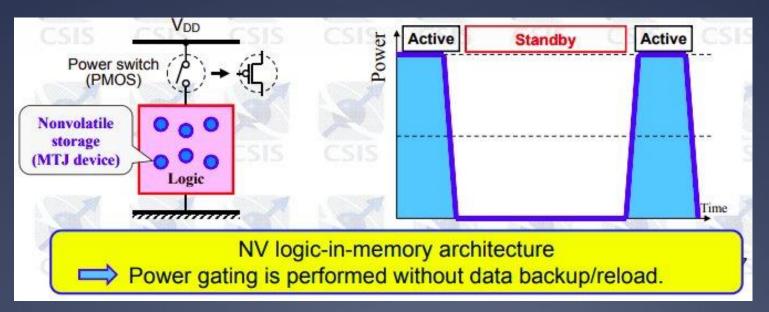
 $V_{T} = V_{FB} + 2\phi_{b} + \gamma_{N}\sqrt{\left(2\phi_{b} - V_{BS}\right)}$ 

### **Power Gating**



# **Memory-in-Logic**

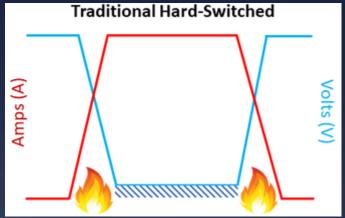


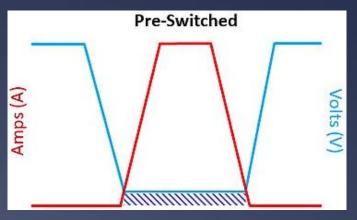


S. Matsunaga et al., "MTJ-based Nonvolatile Logic-in-Memory Architecture and Its Application", 11th Non-volatile Memory Technology Symposium, Shanghai, China, Nov. 9, 2012 ; T. Hanyu et al., "Beyond MRAM : Nonvolatile Logic-in-Memory VLSI", Chapter 7 of Introduction to Magnetic Random-Access Memory

### **Adiabatic Circuits**

- 1. Never turn on a transistor when there is a voltage potential between the source and drain.
- 2. Never turn off a transistor when current is flowing through it.
- recovering or recycling energy in the form of electric charge → power supplies of adiabatic logic circuits have also used circuit elements capable of storing energy.
- 4. Concept (1) and (2) also used in SMPS (Switched Mode Power Supplies). WBG semiconductors make this process very efficient.





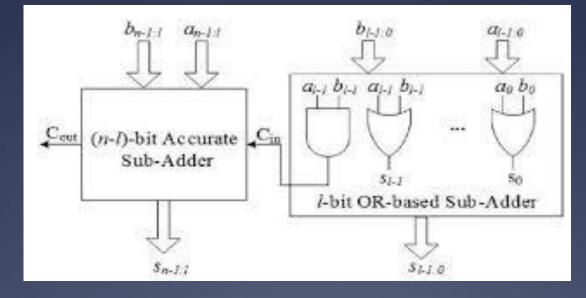
https://www.pre-switch.com/singlepost/2018/05/28/Hard-Switching-Soft-Switching-Pre-Switching

#### **Architectures**

# **Approximate Computing**

- 1. Acceptably inaccurate result rather than a guaranteed accurate result.
- 2. Good for applications like Search engine, Machine Learning, Scientific Computing
- 3. Google using this approach in their Tensor Processing Units (TPUs)

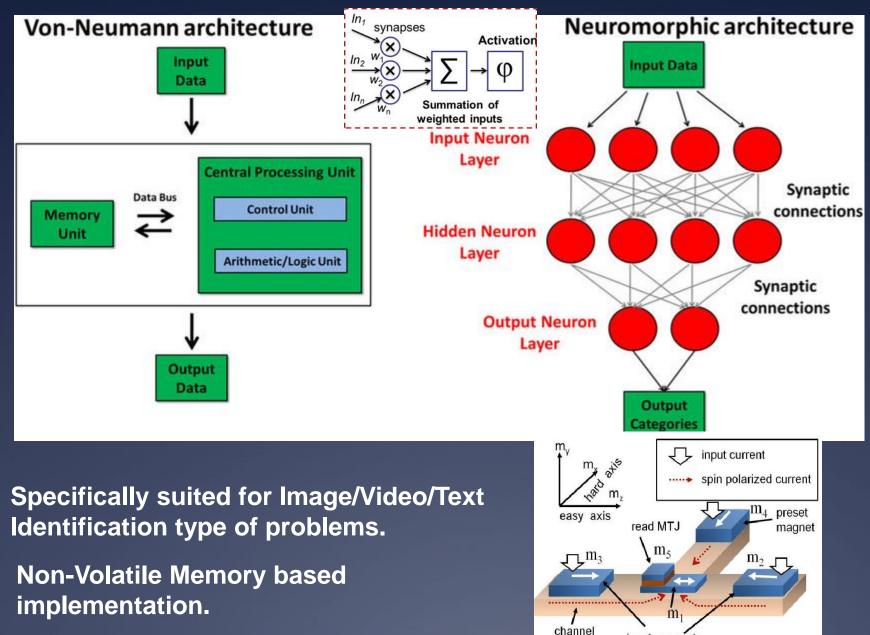
Approx. Adder Circuit



https://www.irjet.net/ar chives/V5/i10/IRJET-V5I10365.pdf

- **1.** Approximate Circuit: reduced hardware. Save energy & area.
- 2. Approximate Storage: Truncate low bits while storing

# **Neuromorphic Computing**



input magnets

### **Quantum Computing**





https://www.nyt imes.com/2019/ 10/23/technolog y/quantumcomputinggoogle.html

- Very specific set of problems like Cryptography, Quantum Simulation for chemistry and drug discovery.
- NASA had bought annealing based Quantum Computer from D-Wave.

#### Summary

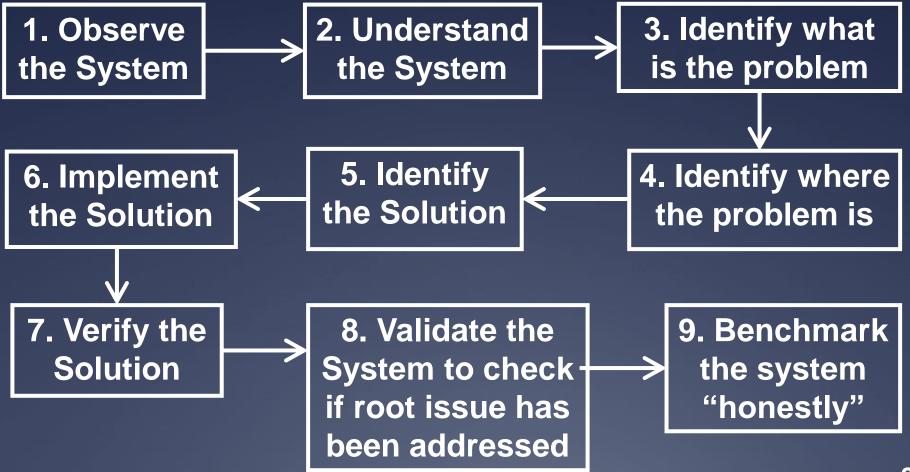
- We are at a cusp of massive change when new generation and type of GreenTech Chips shall enter our lives.
- GreenTech Chips shall see changes which range across materials, devices, circuits and architectures.
- As a designer of a chip or a system around it or an application over it, its suggested to go for first-principle thinking.
- These new solutions are very unlike previous ones and there is no concept of general or universal solution. They are not drop-down replacement of previous technology. So start by understanding the NEED, then SYSTEM, then SOLUTION, and finally do VERIFY and BENCHMARK it.

# **Back-Up**

#### New Applications

# **Suggested Method**

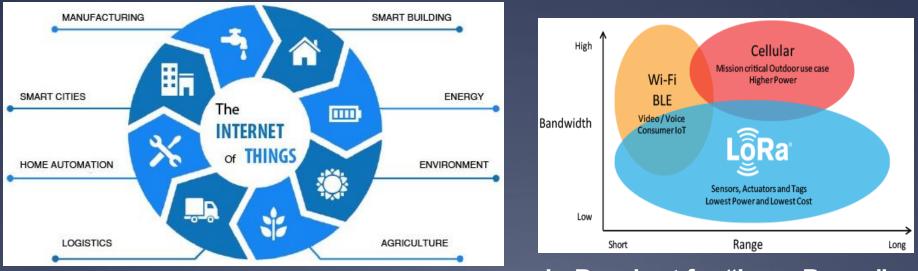
to check if one or more of "New Approach" will actually solve a problem with a GreenTech solution, or is it just going to be a fad or over-design.



### Internet-of-Things (IoT)

Low Battery Drainage, Extreme Low-Power, Energy Harvesting & Bio-Sensing Applications

- Low-Power Wireless [LoRa, LPWAN, FM, BLE], [WiFi ?]
- Analog vs Digital Computing
- Data Analytics [How Frequently ? Edge Vs Cloud ?]
- Security [Really required ? H/w vs S/w Encryption ? Cost ?]



LoRa: short for "Long Range"

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#### Wearables

Consumer Electronics (an unmet " Need " ?)





#### Specialized Applications (Wearable Elec. + e-Textiles)

Examples: Patients, healthcare worker, fire fighters, police/soldiers, mining workers, oil rig platform workers, construction workers, painters, Roofers, electricians, electrical power-line workers, fishers and related fishing workers, underwater welders, jewelry design





### **Heavy Drainage Battery Applications**

Drones, Robots, Electric Vehicles, Nano-Satellites

- Understanding the "Need" (Technology, Market, Customers), e.g.:
  - "Coal-fired plants generate 72% of India's electricity" [13]
  - Norway's 95% electricity is hydropower [14]
  - Solving energy crisis and carbon foot-print

→ Case for EVs for India vs Norway ?

- This shall help decide upon the technology, e.g. for driving motor or charging battery, e.g.:
  - Power-MOSFET vs GaN HEMT
  - SiC FET vs IGBT
  - Switching Frequency & EMI (Electromagnetic Interference)
  - Thermal Constraints & Cooling requirements
  - System Size, Cost & Performance (True Bottleneck ?)

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[6] Pollution Image: https://www.theguardian.com/cities/2019/mar/05/india-home-to-22-of-worlds-30-most-polluted-cities-greenpeace-says

[7] IoT Chip Image: https://www.forbes.com/sites/Iouiscolumbus/2020/05/25/the-top-20-iot-startups-towatch-in-2020/#1a0897bf7697

[8] Electric Vehicle Image: https://thebluecircle.co/2020/04/16/5-electric-vehicle-startups-making-indiaclean-and-green/

[9] Chip with Heat Sink Image: https://lh3.googleusercontent.com/proxy/l8CTCdDd00IG6A0hSuFda5-ONvgy4TLwtv2nVzsvabV-kZIKORwNu5b-5VG64MA7mWxQ5NhNaMMN-

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[13] https://economictimes.indiatimes.com/industry/energy/power/india-will-not-be-able-to-achieve-itsrenewable-energy-targets-anytime-soon/articleshow/69286279.cms

[14] https://en.wikipedia.org/wiki/Renewable\_energy\_in\_Norway#Hydroelectric\_power

[15] Neuromorphic Summation Image: https://dfan.engineering.asu.edu/neuromorphic-computing/

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[17] Spintronic Synapse Image:

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g\_Spin\_Neurons

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Smartwatch/dp/B00BKEQBI0

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[22]Google Glass Image: https://www.theverge.com/2020/2/4/21121472/google-glass-2-enterprise-edition-for-sale-directly-online

[23] E-textile: Hand with circuit Image: https://www.youtube.com/watch?v=cMcQeID6b40

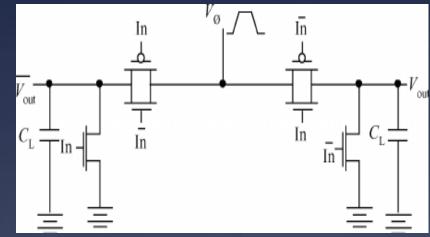
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[25] TFET Image: https://www.wikiwand.com/en/Tunnel\_field-effect\_transistor

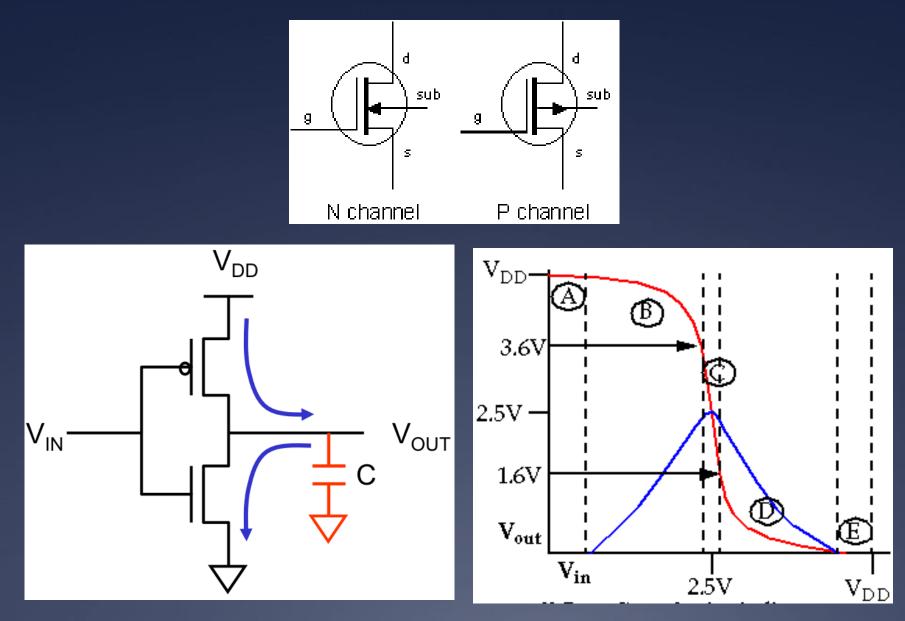
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Adiabatic Adder



https://www.researchgate.net/publication /258308944\_Scaling\_trends\_in\_energy\_re covery\_logic\_An\_analytical\_approach

### Analog, Logic & Memory



#### Chapter 5, CMOS VLSI Design – Weste, 4th edition

 $P_{\text{total}} = P_{\text{dynamic}} + P_{\text{static}}$ 

Other 14%

Memory

20%

Leakage 21% Cores

32%

I/O

13%

### **How is Power Dissipated ?**

Power dissipation in CMOS circuits comes from two components:

- Dynamic dissipation due to  $P_{\text{dynamic}} = P_{\text{switching}} + P_{\text{short circuit}}$ 
  - charging and discharging load capacitances as gates switch
  - "short-circuit" current while both pMOS and nMOS stacks are partially ON
- Static dissipation due to  $P_{\text{static}} = (I_{\text{sub}} + I_{\text{gate}} + I_{\text{junct}} + I_{\text{contention}})V_{DD}$ 
  - subthreshold leakage through OFF transistors
  - gate leakage through gate dielectric
  - junction leakage from source/drain diffusions
  - o contention current in ratioed circuits (see Section 9.2.2) FIGURE 5.6 Power in Niagra2

#### Active Power $\rightarrow$ power consumed while the chip is doing useful work

Standby Power  $\rightarrow$  power consumed while the chip is idle. If clocks are stopped and ratioed circuits are disabled, the standby power is set by leakage.

Sleep Mode  $\rightarrow$  supplies to unneeded circuits are turned off to eliminate leakage  $\rightarrow$  drastically reduces the sleep power required, but the chip requires time and energy to wake up  $\rightarrow$  sleeping is only viable if the chip will idle for long enough.<sup>3</sup>